INDUSTRIAL COMPUTER | BIS-2639



FEATURES

- NXP i.MX8M Plus Quad-core Application Processor, Long Life Cycle
- Onboard 4GB LPDDR4 Memory and High-Endurance iNAND Flash Storage
- Dual Gigabit Ethernet Ports with 12–36V AC/DC Power Input and PoE via RJ-45
- Multiple Industrial Serial Interfaces: RS-232, Dual RS-485
- Rich Wireless Expansion Options via M.2 Sockets (WiFi/BT, LTE/5G, NVMe SSD)
- HDMI Display Output and USB 3.0 (Type-A & Type-C OTG) Interfaces
- Built-in TPM 2.0 Security Module (Infineon SLB 9673)
- Wide Operating Temperature −20°C to +70°C
- Fanless Aluminum Enclosure with VESA Mount / DIN-Rail Support

The BIS-2639 is a compact and fanless IoT gateway embedded PC powered by the NXP i.MX8M Plus quad-core application processor. Designed with long-term reliability and industrial stability, it provides dual Gigabit Ethernet ports, PoE capability, and multiple serial interfaces to meet diverse connectivity needs. With onboard LPDDR4 memory, industrial-grade flash storage, HDMI display output, and modular wireless expansion via M.2 sockets, this gateway is highly adaptable for communication-intensive or edge-AI scenarios. The robust fanless aluminum enclosure with VESA and DIN-rail mounting options makes it ideal for smart gateway, industrial automation, digital signage, kiosks, and various embedded applications.

SPECIFICATIONS

SYSTEM

Processor	i.MX 8M Plus, 4 x ARM Cortex-A53 @ 1.6GHz
Memory	Onboard 4GB LPDDR4
Storage	Onboard iNAND flash (32GB default), 265K EEPROM with write protect control SDIO Micro SD card socket
OS	Yocto Embedded Linux with source code from NXP i.MX8MP EVK reference design, custom drivers
RTC	Included
Security	Infineon SLB 9673 TPM2.0

POWER

Power Input	12-36V AC/DC power input via terminal block, 12V DC via barrel jack, POE via RJ-45

MECHANICAL

Enclosure Material	Aluminum
Enclosure Color	Black
Dimensions	170 x 124 x 39mm (6.7" x 4.9" x 1.54")
Mounting Option	Support 75 x 75mm VESA Mount, or DIN-Rail Mount with Optional Bracket
Cooling	Fanless

I/O INTERFACE

Display Interface	HDMI
External IO	2 x GbE via RJ-45 2 x USB 3.0 Type A, 1 x USB 3.0 Type C OTG 2 x RS-485 via terminal block 1 x RS-232 via DB9
Internal Expansion	1 x M.2 E-key socket (Wifi/BT) SDIO, USB 2.0, I²C, UART 1 x M.2 B-key socket (LTE/5G) USB 3.0, I²C 1 x M.2 M-key socket (SSD), dedicated PCIe 3.0 1 x Lane for NVMe
Antenna	4 x u.FL to SMA bulkhead connectors
Software update interface	USB or micro SD

ENVIRONMENTAL

Temperature:	
- Operation	-20°C to 70°C
- Storage	-40°C to 85°C
Environmental	IP-20 or better

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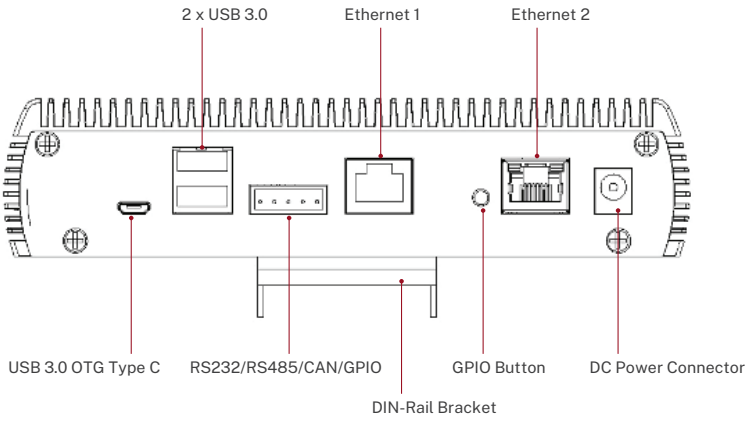
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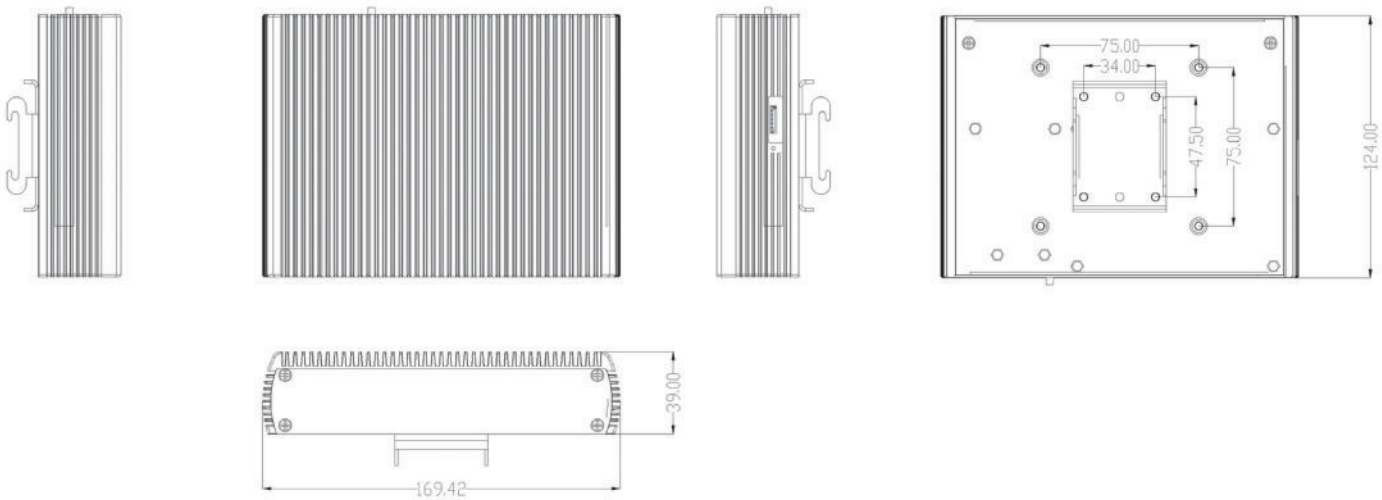
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SYSTEM LAYOUT



PRODUCT DIMENSIONS

Unit: mm



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